SN74LV573A 具有三态输出的八路透明 D 类锁存器

1 特性

- V_{CC} 工作范围为 2V 至 5.5V
- 电压为 5V 时，t_{pd} 最大值为 8ns
- V_{CC} = 3.3V、T_A = 25°C 时，V_{OLP}（输出接地反弹）典型值小于 0.8V，闩锁性能超过 250mA
- V_{CC} = 3.3V、T_A = 25°C 时，V_{OHV}（输出 V_{OH} 下冲）典型值大于 2.3V
- 所有端口上均支持混合模式电压运行
- I_{off} 支持局部断电模式运行
- 闩锁性能超过 250mA，符合 JESD 17 规范

2 应用

- 缓冲寄存器
- 双向总线驱动器
- 工作寄存器

连接至其他七个通道

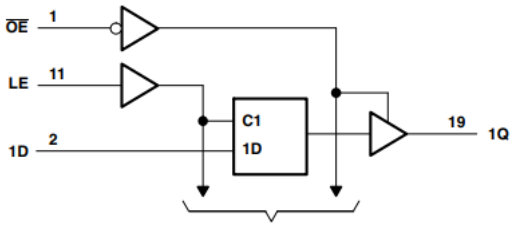
3 说明

'LV573A 器件为八路透明 D 类锁存器，可在 2V 至 5.5V V_{CC} 下运行。

封装信息(1)

器件型号	封装	封装尺寸（标称值）
SN74LV573A	NS（SO，20）	12.6 mm × 5.3 mm
	DW（SOIC，20）	12.8mm × 7.5mm
	DB（SSOP，20）	7.2 mm × 5.3 mm
	PW（TSSOP，20）	6.5mm × 4.4mm
	DGV（TVSOP，20）	5mm × 4.4mm
	RGY（VQFN，20）	4.5mm × 3.5mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



逻辑图（正逻辑）

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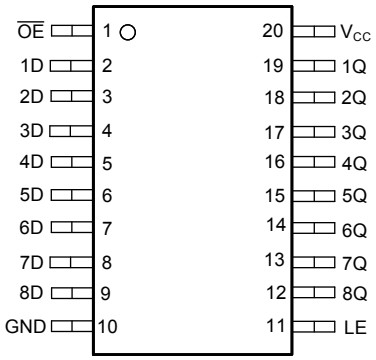
4 Revision History

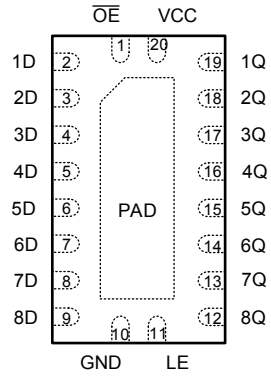
注：以前版本的页码可能与当前版本的页码不同

Changes from Revision I (April 2005) to Revision J (March 2023)	Page
• 添加了*应用*、*封装信息* 表、*引脚功能* 表、*ESD 等级* 表、*热性能信息* 表、*器件功能模式*、*应用和实施* 部分、*电源相关建议* 部分、*布局* 部分、*器件和文档支持* 部分以及*机械、封装和可订购信息* 部分	1
• Updated thermal values for PW package from R θ JA = 131.8 to 128.2, all values in °C/W	5

5 Pin Configuration and Functions



DB, DGV, DW, NS, or PW Packages Top View



RGY Package Top View

表 5-1. Pin Functions

PIN		I/O[1]	DESCRIPTION
NO.	NAME		
1	$\overline{OE}$	I	Output enable
2	1D	I	1D input
3	2D	I	2D input
4	3D	I	3D input
5	4D	I	4D input
6	5D	I	5D input
7	6D	I	6D input
8	7D	I	7D input
9	8D	I	8D input
10	GND	—	Ground
11	LE	I	Latch enable input
12	8Q	O	8Q output
13	7Q	O	7Q output
14	6Q	O	6Q output
15	5Q	O	5Q output
16	4Q	O	4Q output
17	3Q	O	3Q output
18	2Q	O	2Q output
19	1Q	O	1Q output
20	V_{CC}	—	Power pin

1. I = Input, O = Output, I/O = Input or Output, G = Ground, P = Power.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		– 0.5	7	V
V_I	Input voltage(1)		– 0.5	7	V
V_O	Voltage range applied to any output in the high-impedance or power-off state(1)		– 0.5	7	V
V_O	Output voltage range applied in the high or low state(1) (2)		– 0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current(2)	V_I < 0		±20	mA
I_{OK}	Output clamp current(2)	V_O < 0		−50	mA
I_O	Continuous output current	V_O = 0 to V_{CC}		±35	mA
	Continuous current through V_{CC} or GND			±70	mA
T_{stg}	Storage temperature		– 65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-Body Model (A114-A)(1)	±2000	V
		Charged-Device Model (C101)(2)	±1000	
		Machine Model (A115-A)	±200	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5		V
		V_{CC} = 2.3 V to 2.7 V	V_{CC} × 0.7		
		V_{CC} = 3 V to 3.6 V	V_{CC} × 0.7		
		V_{CC} = 4.5 V to 5.5 V	V_{CC} × 0.7		
V_{IL}	Low-level input voltage	V_{CC} = 2 V		0.5	V
		V_{CC} = 2.3 V to 2.7 V		V_{CC} × 0.3	
		V_{CC} = 3 V to 3.6 V		V_{CC} × 0.3	
		V_{CC} = 4.5 V to 5.5 V		V_{CC} × 0.3	
V_I	Input voltage		0	5.5	V
V_O	Output voltage	High or low state	0	V_{CC}	V
		3-state	0	5.5	
I_{OH}	High-level output current	V_{CC} = 2 V		− 50	ns
		V_{CC} = 2.3 V to 2.7 V		− 2	
		V_{CC} = 3 V to 3.6 V		− 8	
		V_{CC} = 4.5 V to 5.5 V		− 16	

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
I_{OL}	Low-level output current	V_{CC} = 2 V		50	ns
		V_{CC} = 2.3 V to 2.7 V		2	
		V_{CC} = 3 V to 3.6 V		8	
		V_{CC} = 4.5 V to 5.5 V		16	
$\Delta t/\Delta v$	Input transition rise or fall rate	V_{CC} = 2.3 V to 2.7 V		200	ns
		V_{CC} = 3 V to 3.6 V		100	
		V_{CC} = 4.5 V to 5.5 V		20	
T_A	Operating free-air temperature		−40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the *Implications of Slow or Floating CMOS Inputs* application report (SCBA004).

6.4 Thermal Information

THERMAL METRIC		SN74LV573A						UNIT
		DGV (TVSOP)	DW (SOIC)	DB (SSOP)	NS (SO)	PW (TSSOP)	RGY (VQFN)	
		20 PINS	20 PINS	20 PINS	20 PINS	20 PINS	20 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance(1)	92	109.1	122.7	84.6	128.2	37	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
V_{OH}	I_{OH} = −50 μA	2 V to 5.5 V	V_{CC} −0.1			V
	I_{OH} = −2 mA	2.3 V	2			
	I_{OH} = −8 mA	3 V	2.48			
	I_{OH} = −16 mA	4.5 V	3.8			
V_{OL}	I_{OL} = 50 μA	2 V to 5.5 V			0.1	V
	I_{OL} = 2 mA	2.3 V			0.4	
	I_{OL} = 8 mA	3 V			0.44	
	I_{OL} = 16 mA	4.5 V			0.55	
I_I	V_I = 5.5 V or GND	0 to 5.5 V			± 1	μA
I_{OZ}	V_O = V_{CC}or GND	5.5 V			±5	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			20	μA
I_{off}	V_I or V_O = 0 to 5.5 V	0			5	μA
C_i	V_I = V_{CC} or GND	3.3 V		1.8		pF

6.6 Timing Requirements, V_{CC} = 2.5 V ± 0.2 V

over operating free-air temperature range, V_{CC} = 2.5 V ± 0.2 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T_A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
t_w	Pulse duration	LE high	5		5		ns
t_{su}	Setup time	Data before LE ↓	3.5		3.5		ns
t_h	Hold time	Data after LE ↓	1.5		1.5		ns

6.7 Timing Requirements, V_{CC} = 3.3 V ± 0.3 V

over operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T_A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
t_w	Pulse duration	LE high	5		5		ns
t_{su}	Setup time	Data before LE ↓	3.5		3.5		ns
t_h	Hold time	Data after LE ↓	1.5		1.5		ns

6.8 Timing Requirements, V_{CC} =5 V ± 0.5 V

over operating free-air temperature range, V_{CC} = 5 V ± 0.5 V(unless otherwise noted)

PARAMETER		TEST CONDITIONS	T_A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
t_w	Pulse duration	LE high	5		5		ns
t_{su}	Setup time	Data before LE ↓	3.5		3.5		ns
t_h	Hold time	Data after LE ↓	1.5		1.5		ns

6.9 Switching Characteristics, V_{CC} = 2.5 V ± 0.2 V

over operating free-air temperature range, V_{CC} = 2.5 V ± 0.2 V (unless otherwise noted; see Load Circuit and Voltage Waveforms)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN74LV573A		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	D	Q	C_L = 15 pF		8.9[1]	15.8[1]	1	18	ns
t_{pd}	LE	Q			9.6[1]	16.2[1]	1	19	
t_{en}	$\overline{OE}$	Q			9.3[1]	16.2[1]	1	19	
t_{dis}	$\overline{OE}$	Q			6.7[1]	12.6[1]	1	15	
t_{pd}	D	Q	C_L = 50 pF		10.9	18.7	1	21	ns
t_{pd}	LE	Q			11.6	19.1	1	23	
t_{en}	$\overline{OE}$	Q			11.4	19	1	22	
t_{dis}	$\overline{OE}$	Q			8.6	17.3	1	19	
$t_{sk(o)}$						2		2	

1. On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.10 Switching Characteristics, V_{CC} = 3.3 V ± 0.3 V

over operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted; see Load Circuit and Voltage Waveforms)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN74LV573A		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	D	Q	C_L = 15 pF		6.2[1]	11[1]	1	13	ns
t_{pd}	LE	Q			6.8[1]	11.9[1]	1	14	
t_{en}	$\overline{OE}$	Q			6.6[1]	11.5[1]	1	13.5	
t_{dis}	$\overline{OE}$	Q			4.9[1]	11[1]	1	13	
t_{pd}	D	Q	C_L = 50 pF		7.7	14.5	1	16.5	ns
t_{pd}	LE	Q			8.2	15.4	1	17.5	
t_{en}	$\overline{OE}$	Q			8	15	1	17	
t_{dis}	$\overline{OE}$	Q			6.2	14.5	1	16.5	
$t_{sk(o)}$						1.5		1.5	

1. On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.11 Switching Characteristics, 5 V ± 0.5 V

over operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted; see Load Circuit and Voltage Waveforms)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN74LV573A		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	D	Q	C_L = 15 pF		4.3[1]	6.8[1]	1	8	ns
t_{pd}	LE	Q			4.7[1]	7.7[1]	1	9	
t_{en}	$\overline{OE}$	Q			4.7[1]	7.7[1]	1	9	
t_{dis}	$\overline{OE}$	Q			3.5[1]	7.7[1]	1	9	
t_{pd}	D	Q	C_L = 50 pF		5.3	8.8	1	10	ns
t_{pd}	LE	Q			5.7	9.7	1	11	
t_{en}	$\overline{OE}$	Q			5.7	9.7	1	11	
t_{dis}	$\overline{OE}$	Q			4.2	9.7	1	11	
$t_{sk(o)}$						1		1	

1. On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.12 Noise Characteristics

V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C

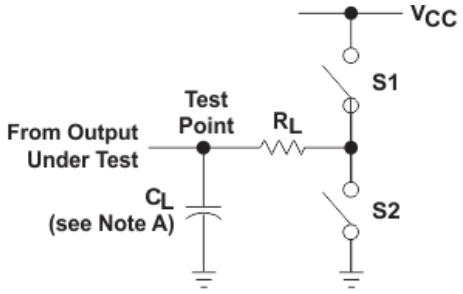
PARAMETER		SN74LV573A			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.6	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		−0.5	−0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		2.9		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

6.13 Operating Characteristics

T_A = 25°C

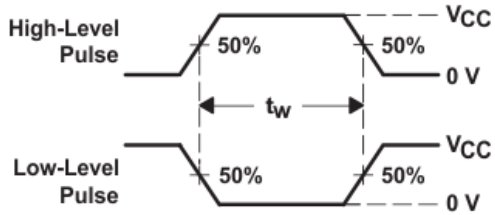
PARAMETER				TEST CONDITIONS		V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	Outputs enabled	D to Q	C_L = 50 pF,	f = 10 MHz	3.3 V	16	pF
						5 V	18	
						3.3 V	18.2	
			LE to Q			5 V	21.3	

7 Parameter Measurement Information

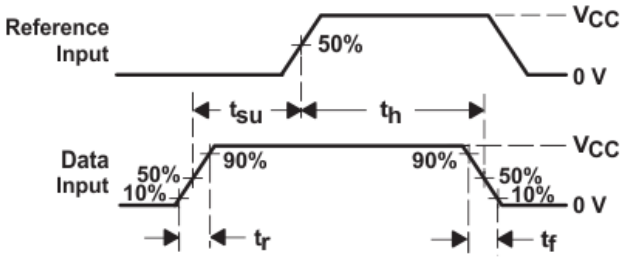


LOAD CIRCUIT

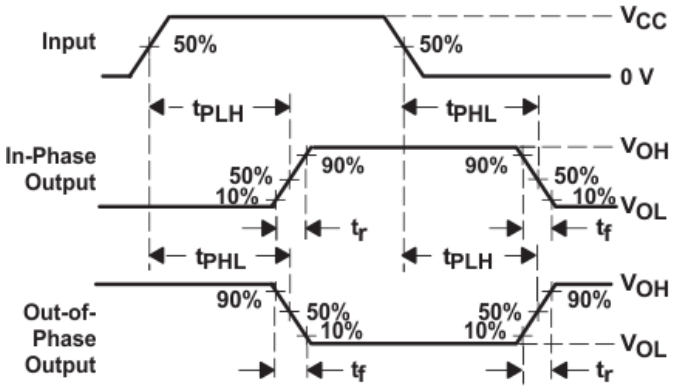
PARAMETER		R_L	C_L	S1	S2
t_{en}	t_{PZH}	1 kΩ	50 pF or 150 pF	Open	Closed
	t_{PZL}			Closed	Open
t_{dis}	t_{PHZ}	1 kΩ	50 pF	Open	Closed
	t_{PLZ}			Closed	Open
t_{pd} or t_t		--	50 pF or 150 pF	Open	Open



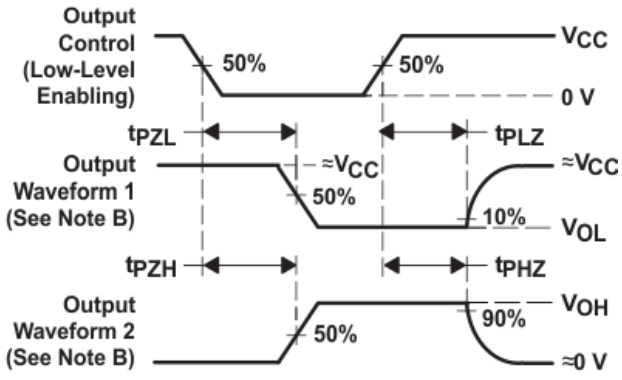
VOLTAGE WAVEFORMS
PULSE DURATIONS



VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

图 7-1. Load Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

The 'LV573A devices feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. This device is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

8.2 Functional Block Diagram

To seven other channels

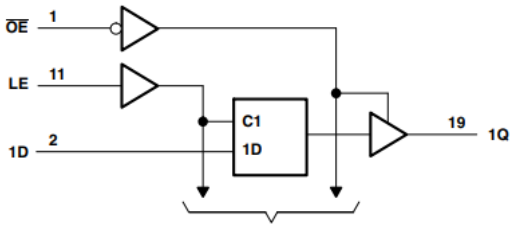


图 8-1. Logic Diagram (Positive Logic)

8.3 Device Functional Modes

表 8-1 lists the functional modes of the SN74LV573A.

表 8-1. Function Table (Each Latch)

INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

9 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客 户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

9.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the 节 6.3 table. The total current through Ground or V_{CC} must not exceed ±70 mA as per 节 6.1 table.

Each V_{CC} pin must have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends 0.1-µF capacitor; if there are multiple V_{CC} pins, then TI recommends 0.01-µF or 0.022-µF capacitor for each power pin. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. A 0.1-µF and 1-µF capacitor are commonly used in parallel. The bypass capacitor must be installed as close to the power pin as possible for best results.

9.2 Layout

9.2.1 Layout Guidelines

When using multiple-bit logic devices, inputs must never float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input and the gate are used, or only 3 of the 4 buffer gates are used. Such input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Layout Diagram specifies the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, they are tied to GND or V_{CC}, whichever makes more sense or is more convenient. It is acceptable to float outputs, unless the part is a transceiver. If the transceiver has an output enable pin, it disables the output section of the part when asserted. This does not disable the input section of the I/Os, so they cannot float when disabled.

9.2.1.1 Layout Example

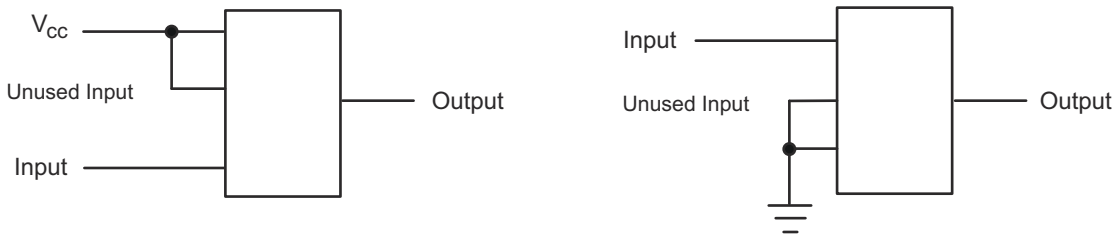


图 9-1. Layout Diagram

10 Device and Documentation Support

10.1 Documentation Support

10.1.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

表 10-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74LV573A	Click here	Click here	Click here	Click here	Click here

10.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 *订阅更新* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

10.3 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

Trademarks

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10.4 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

10.5 术语表

TI 术语表　　本术语表列出并解释了术语、首字母缩略词和定义。

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV573ADBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV573A	Samples
SN74LV573ADBRG4	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV573A	Samples
SN74LV573ADGVR	ACTIVE	TVSOP	DGV	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV573A	Samples
SN74LV573ADW	LIFEBUY	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV573A	
SN74LV573ADWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV573A	Samples
SN74LV573ANSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV573A	Samples
SN74LV573APWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV573A	Samples
SN74LV573APWRG4	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV573A	Samples
SN74LV573ARGYR	ACTIVE	VQFN	RGY	20	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LV573A	Samples
SN74LV573ARGYRG4	ACTIVE	VQFN	RGY	20	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LV573A	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

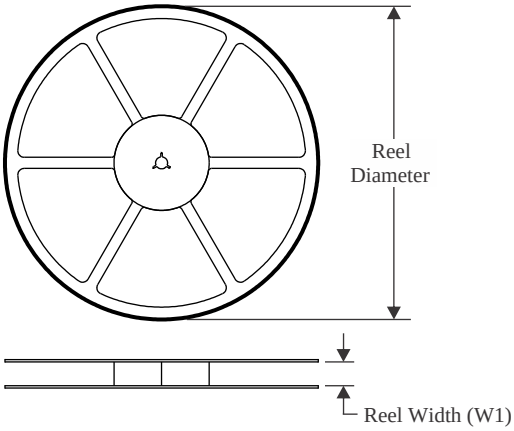
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

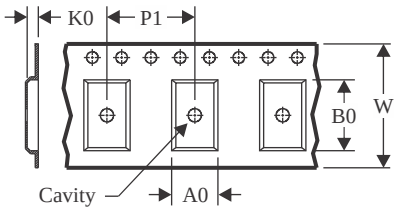
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

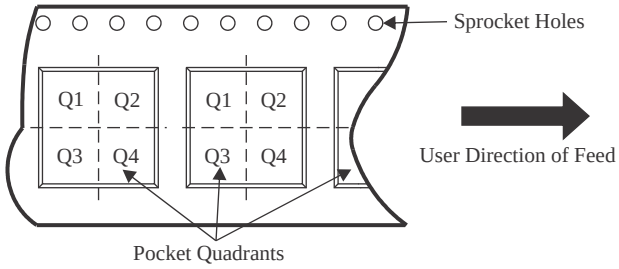


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

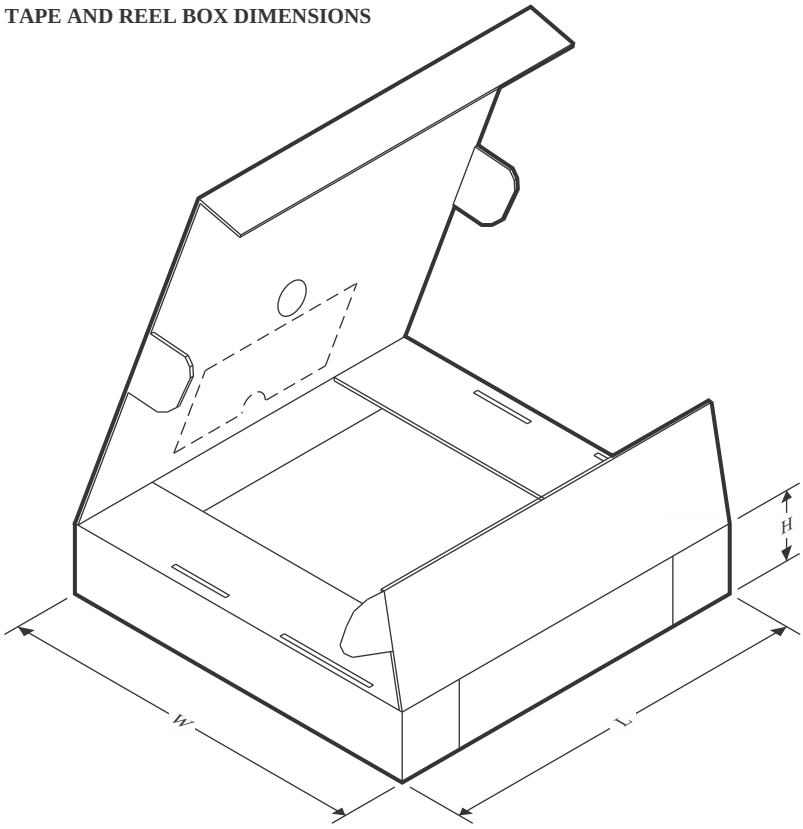
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV573ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LV573ADGVR	TVSOP	DGV	20	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV573ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LV573ANSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74LV573APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74LV573APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74LV573ARGYR	VQFN	RGY	20	3000	330.0	12.4	3.8	4.8	1.6	8.0	12.0	Q1

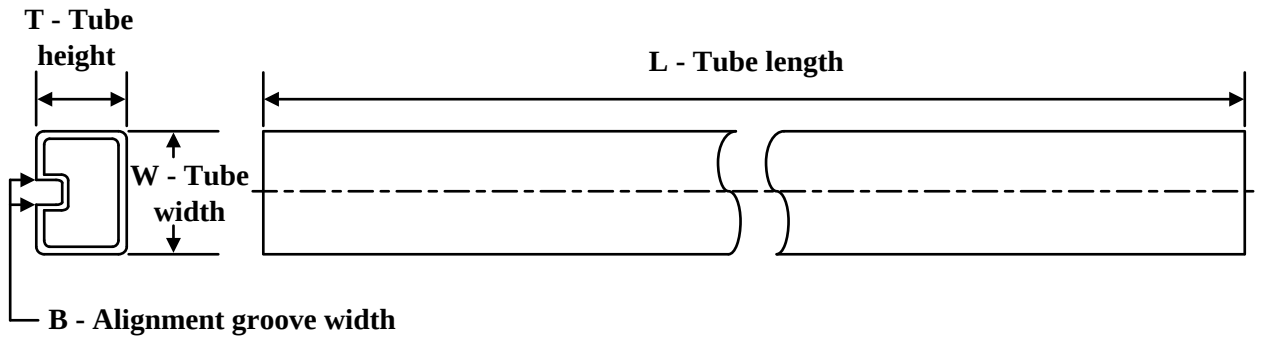
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV573ADBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74LV573ADGVR	TVSOP	DGV	20	2000	356.0	356.0	35.0
SN74LV573ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LV573ANSR	SO	NS	20	2000	367.0	367.0	45.0
SN74LV573APWR	TSSOP	PW	20	2000	356.0	356.0	35.0
SN74LV573APWR	TSSOP	PW	20	2000	356.0	356.0	35.0
SN74LV573ARGYR	VQFN	RGY	20	3000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

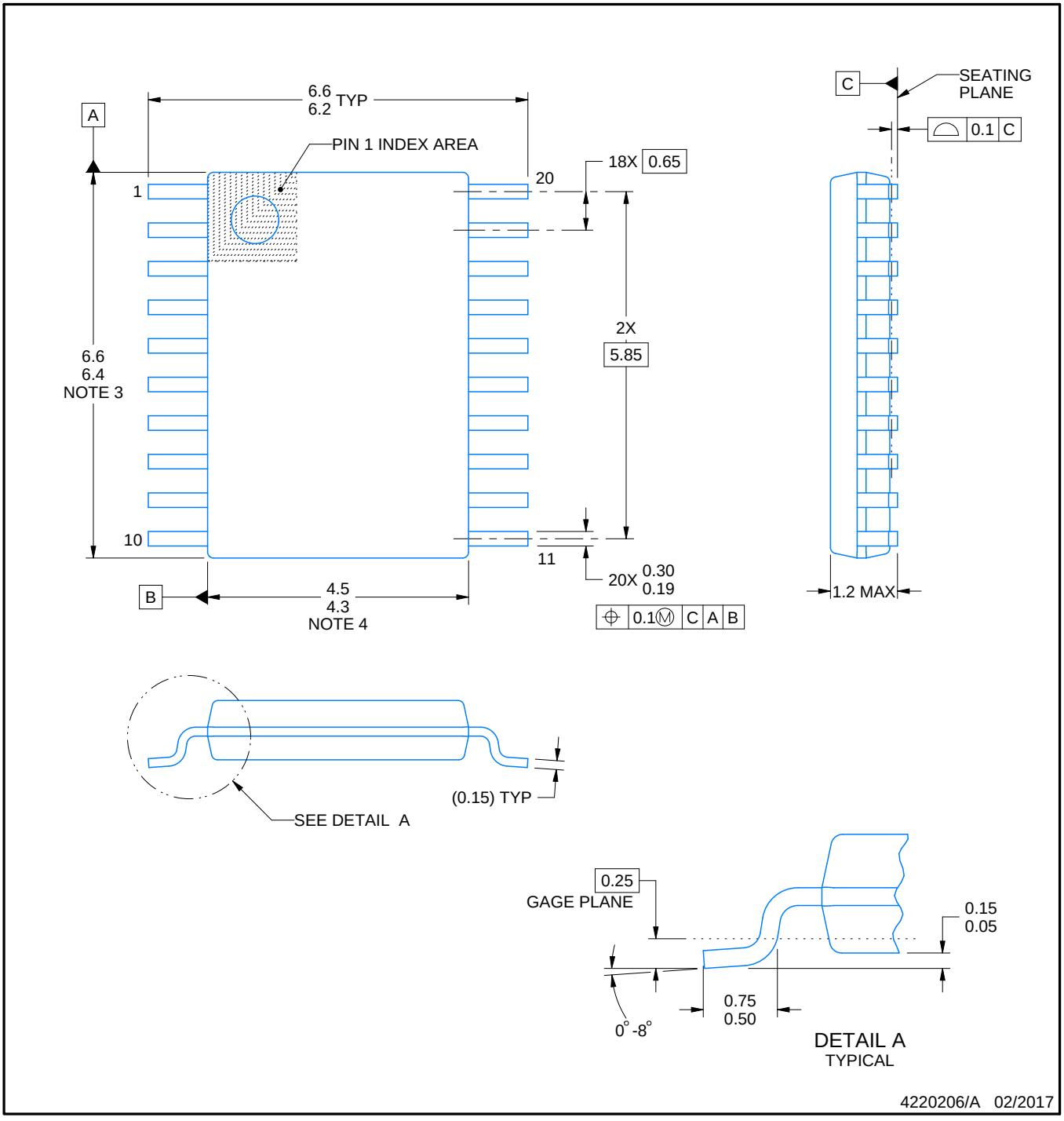
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LV573ADW	DW	SOIC	20	25	507	12.83	5080	6.6

PACKAGE OUTLINE

PW0020A

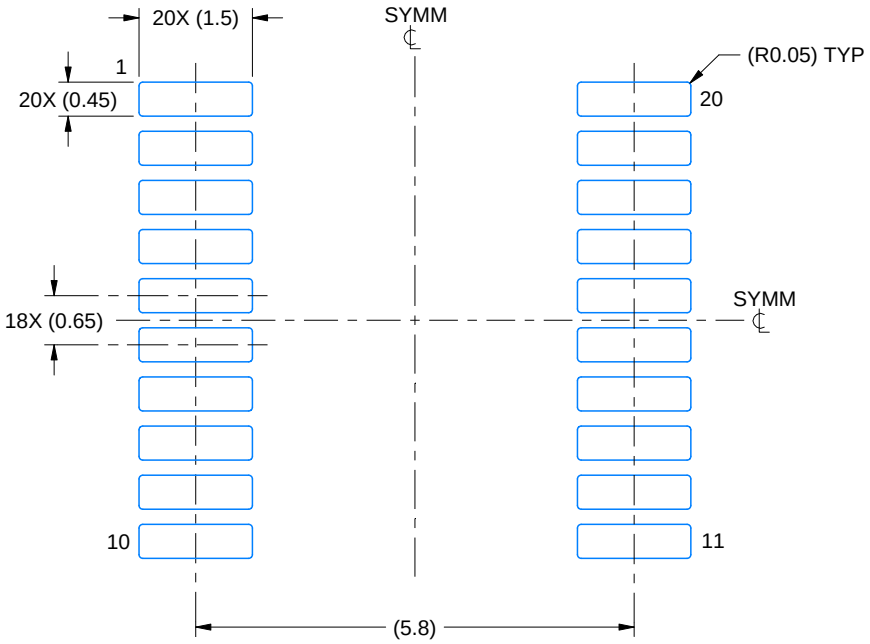
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



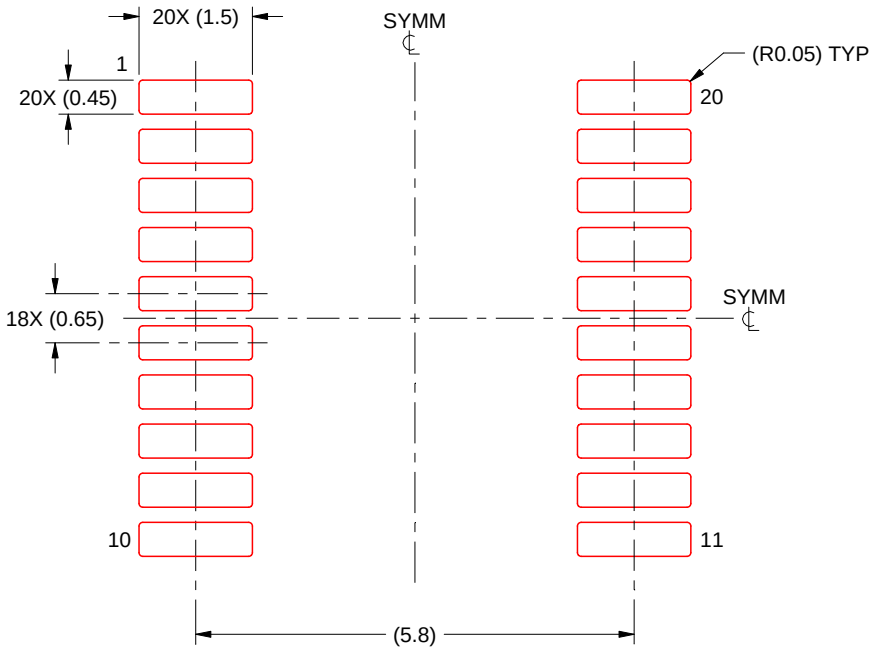
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

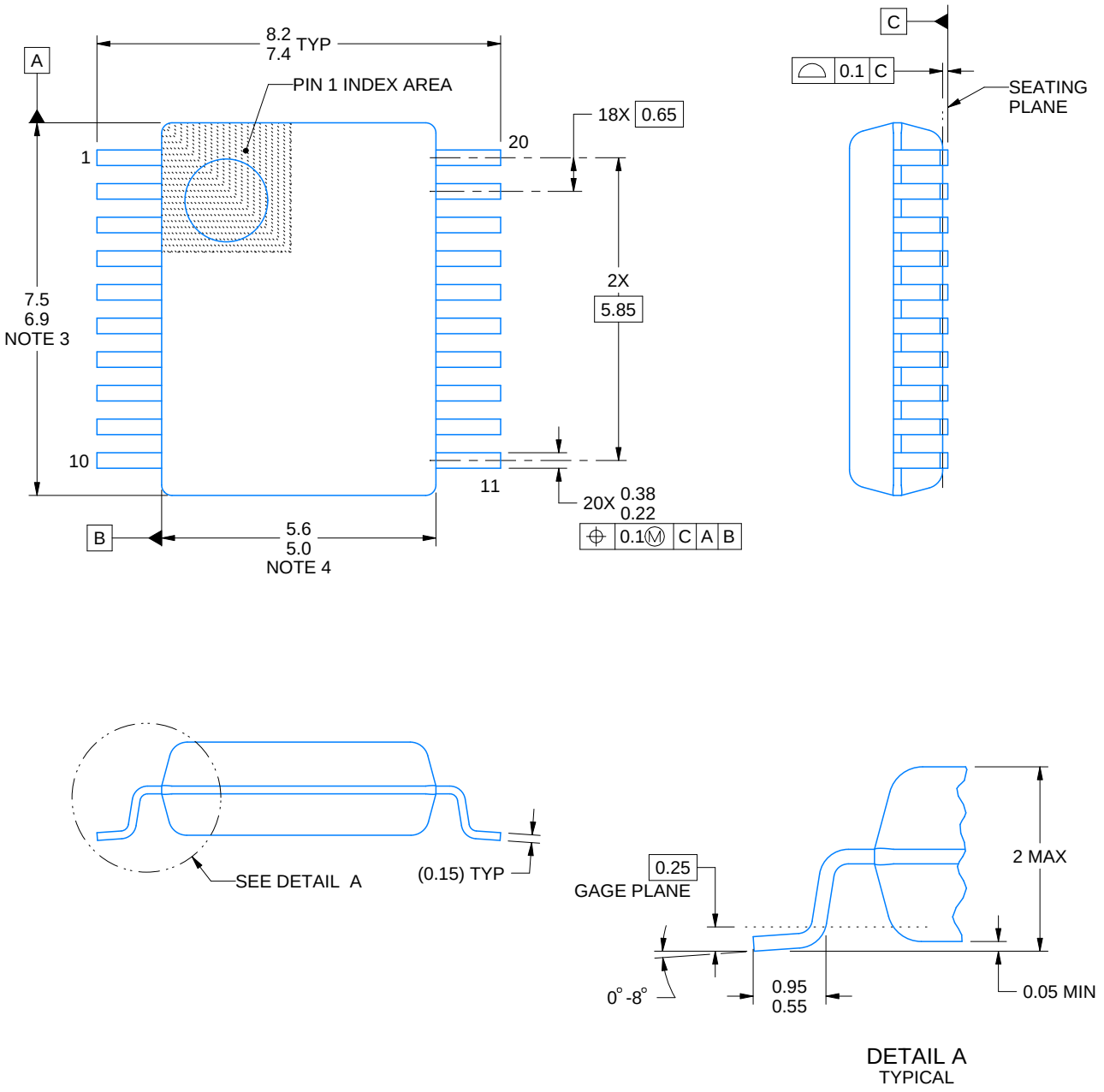
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

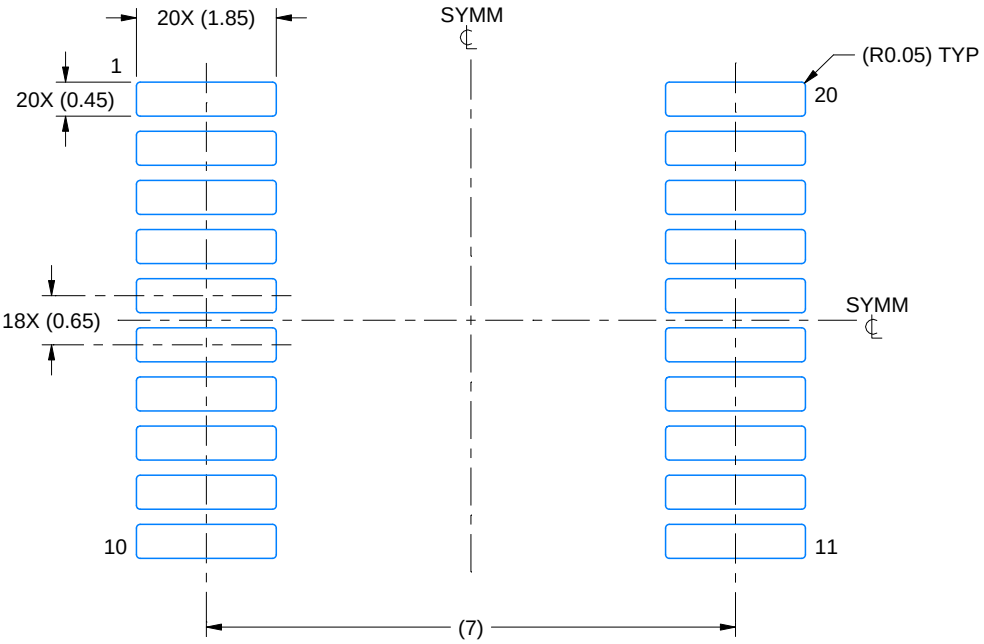
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

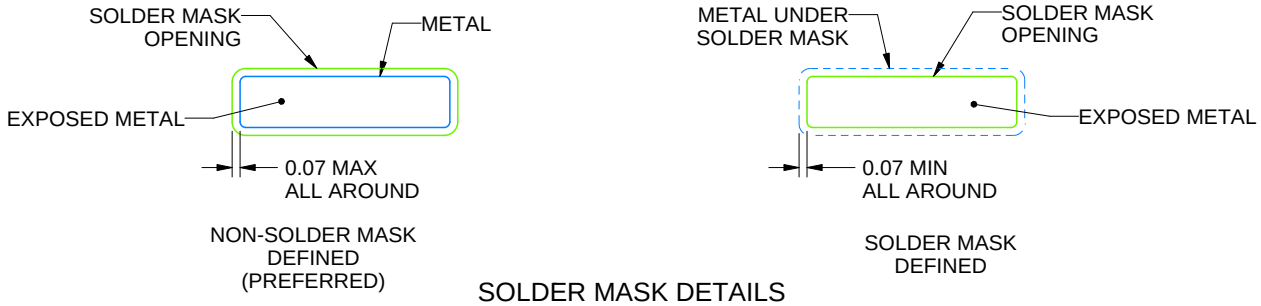
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

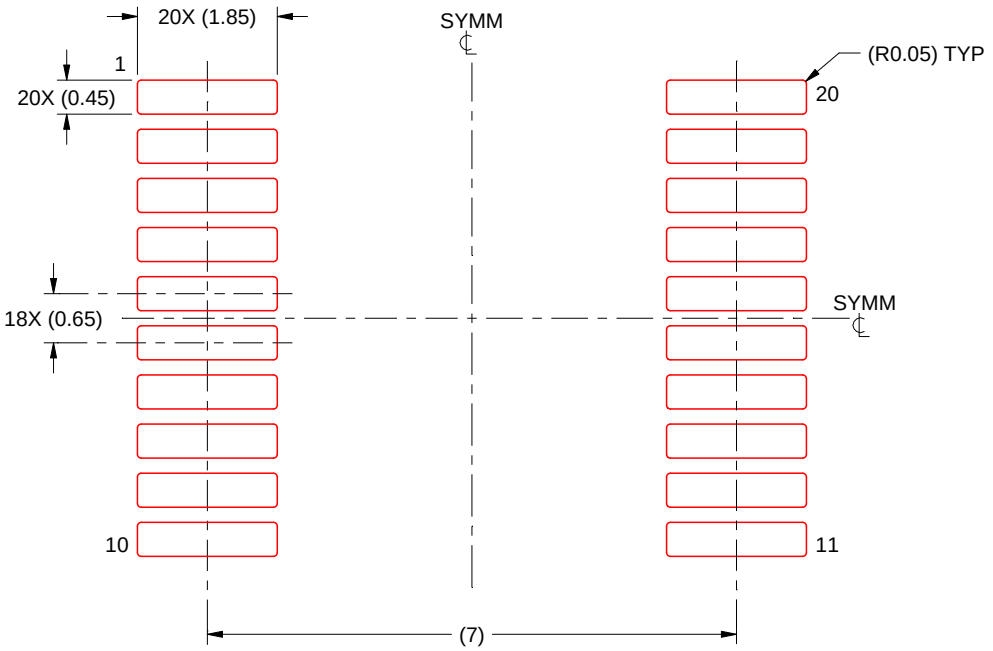
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

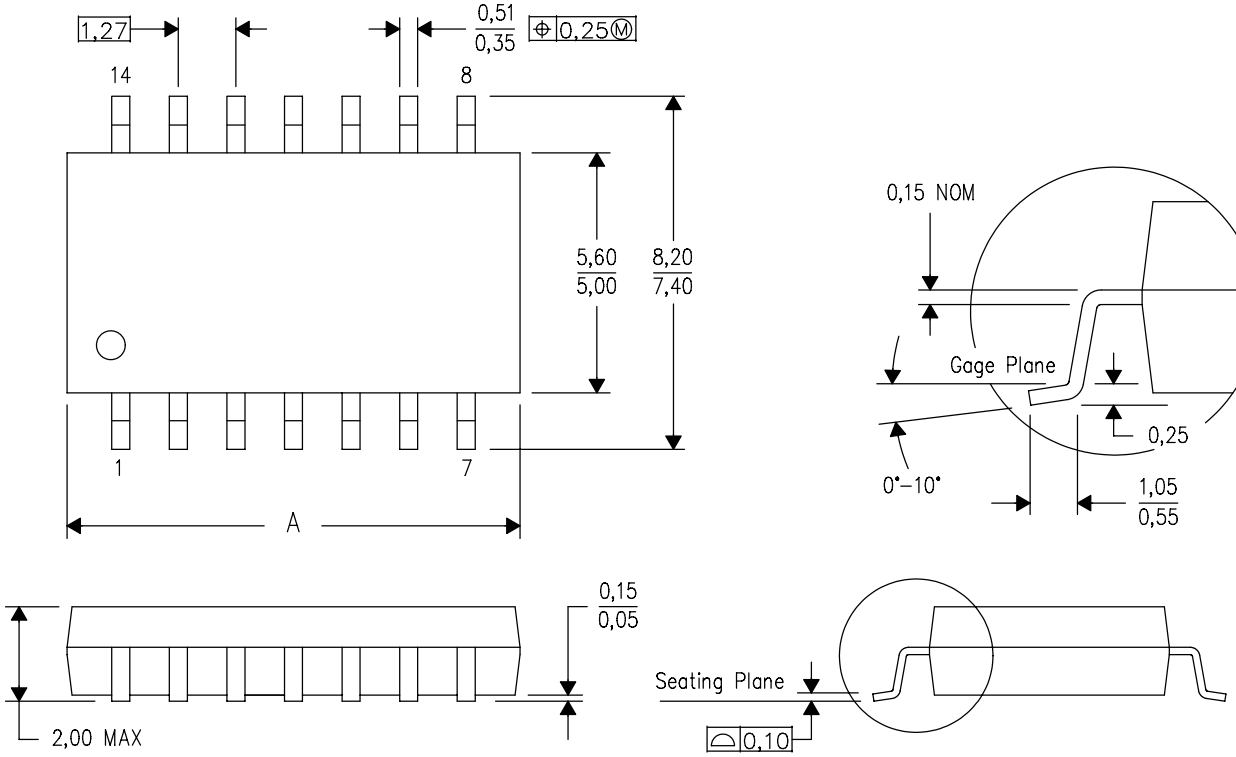
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



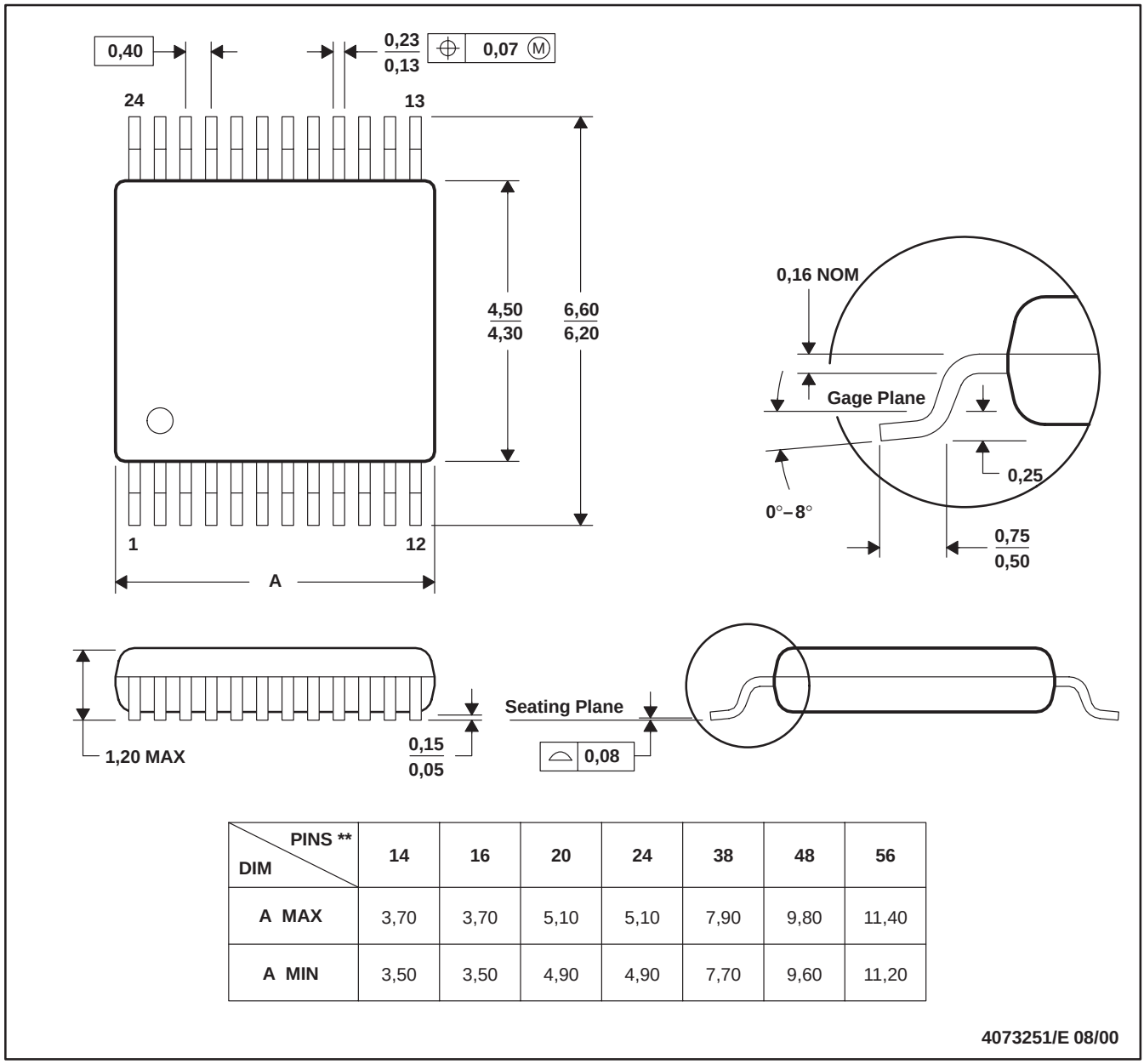
DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DGV (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN



DIM \ PINS **	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

GENERIC PACKAGE VIEW

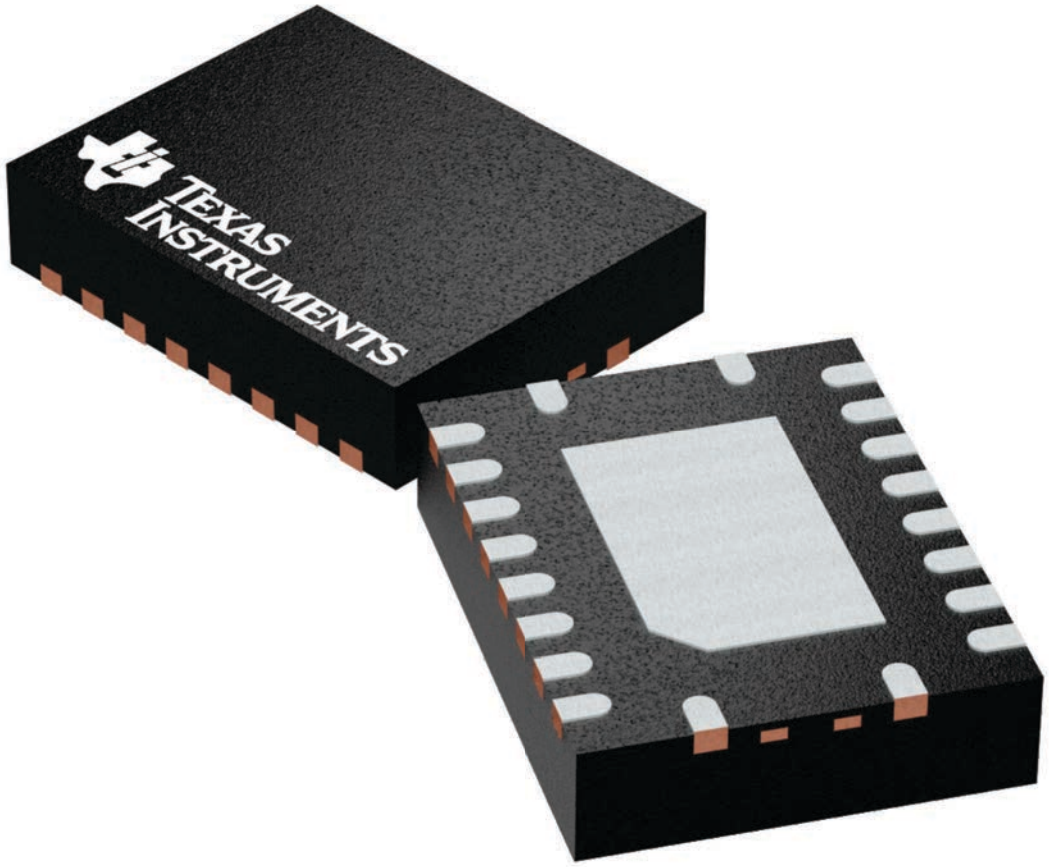
RGY 20

VQFN - 1 mm max height

3.5 x 4.5, 0.5 mm pitch

PLASTIC QUAD FGLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



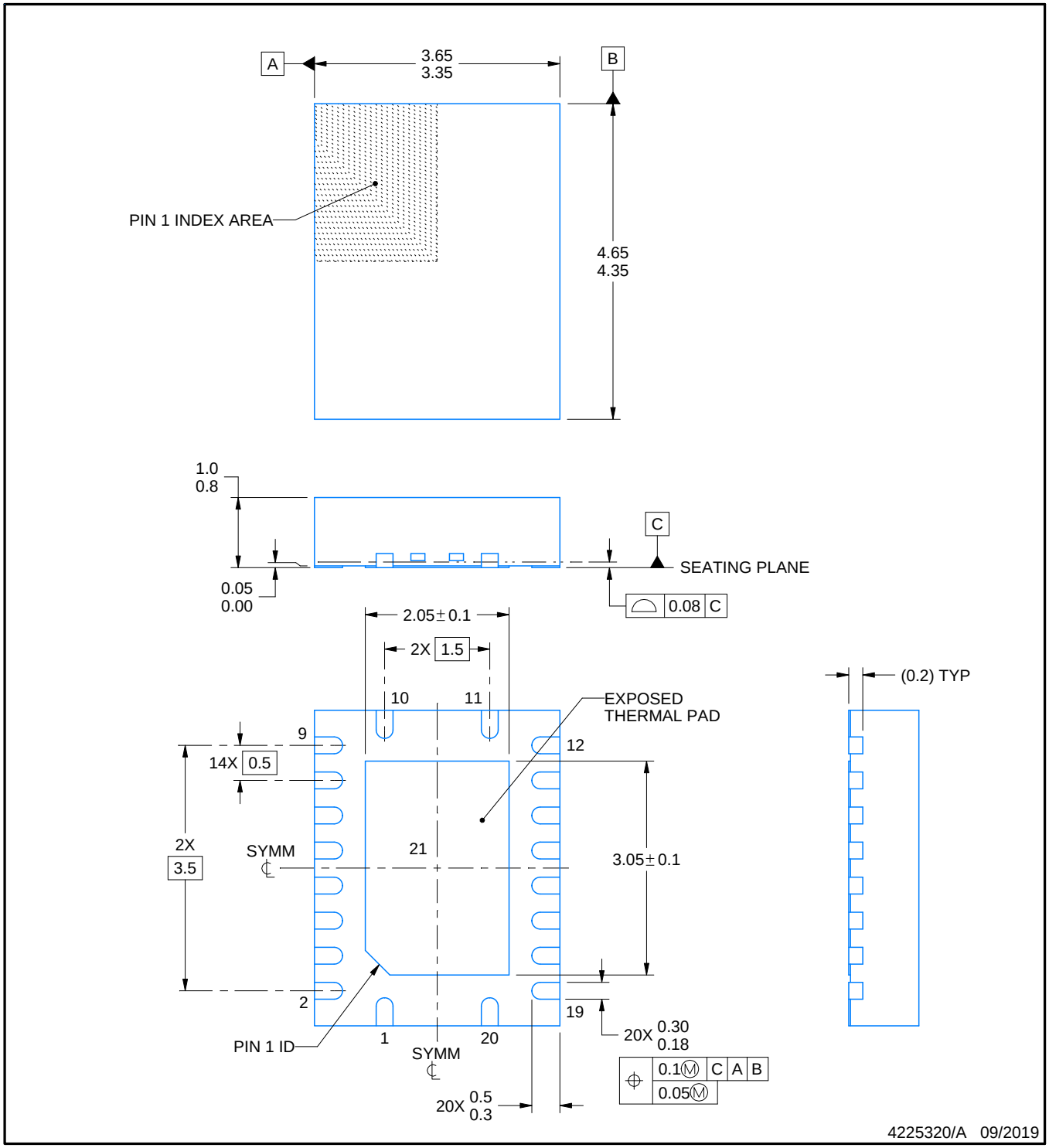
4225264/A

PACKAGE OUTLINE

RGY0020A

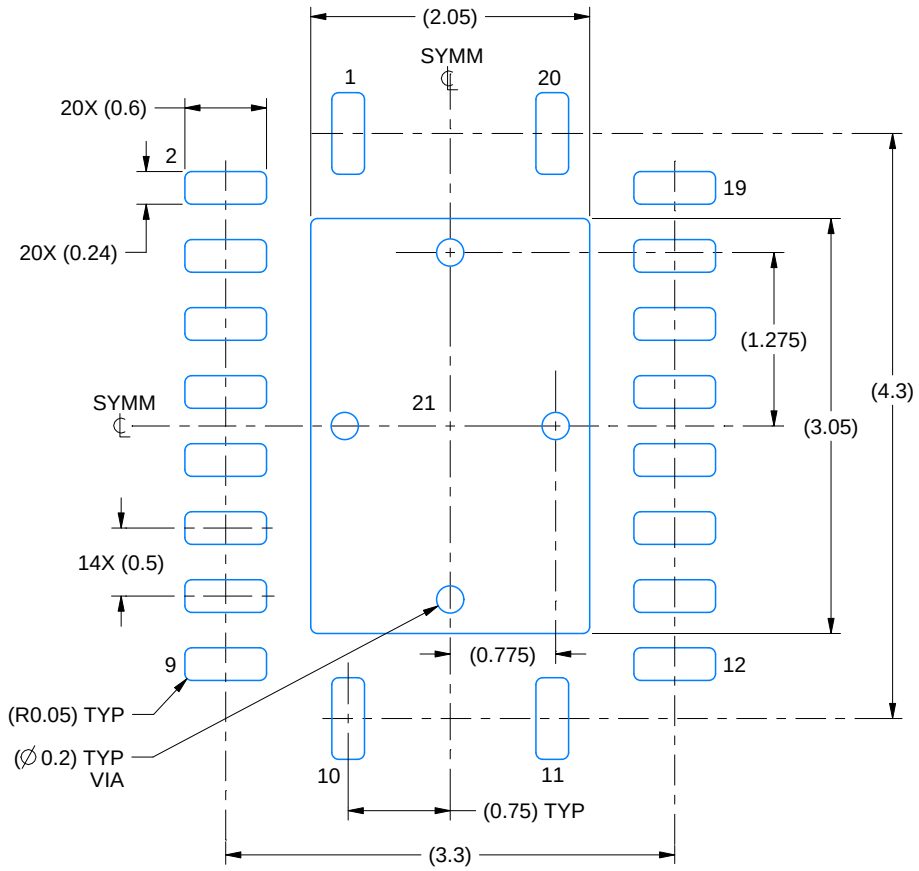
VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

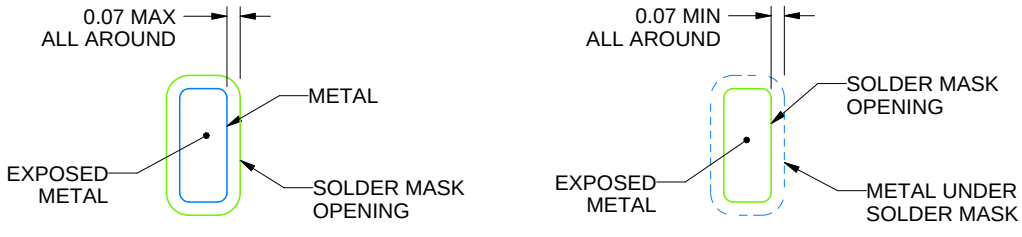


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X



SOLDER MASK DETAILS

4225320/A 09/2019

NOTES: (continued)

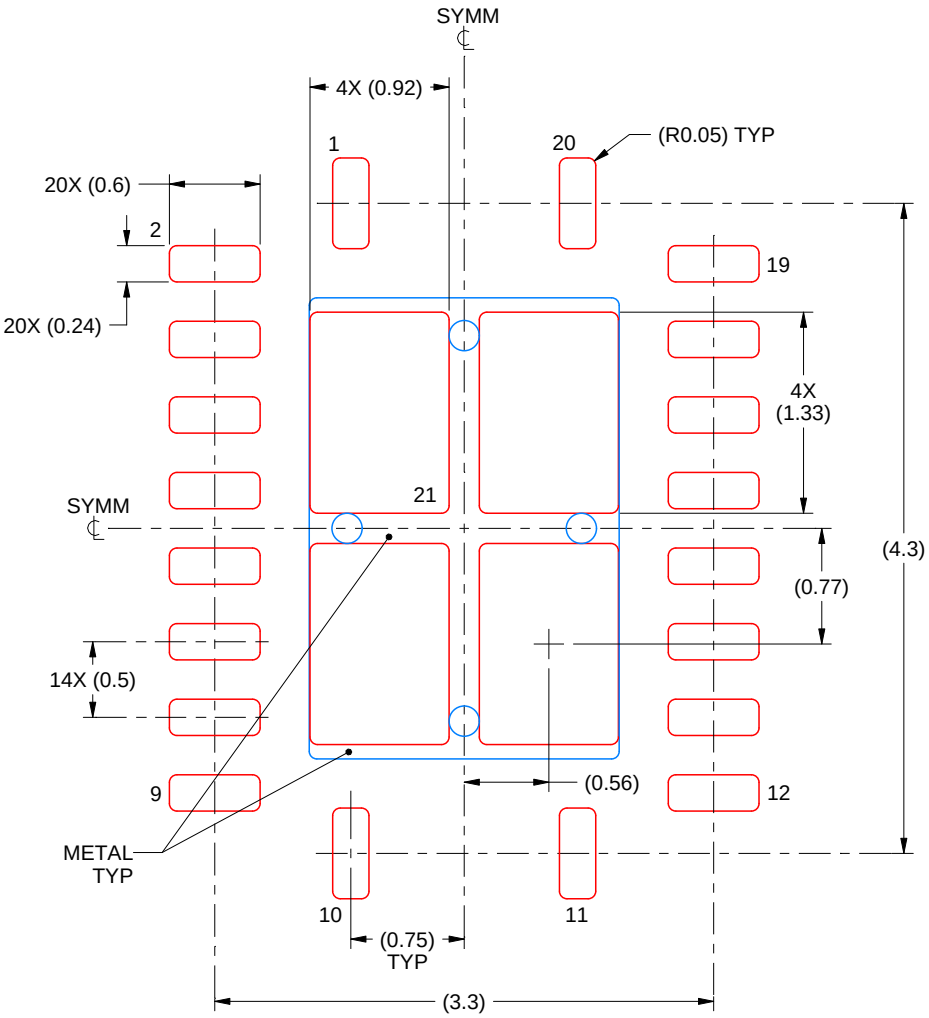
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RGY0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



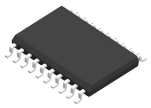
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 21
78% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:20X

4225320/A 09/2019

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

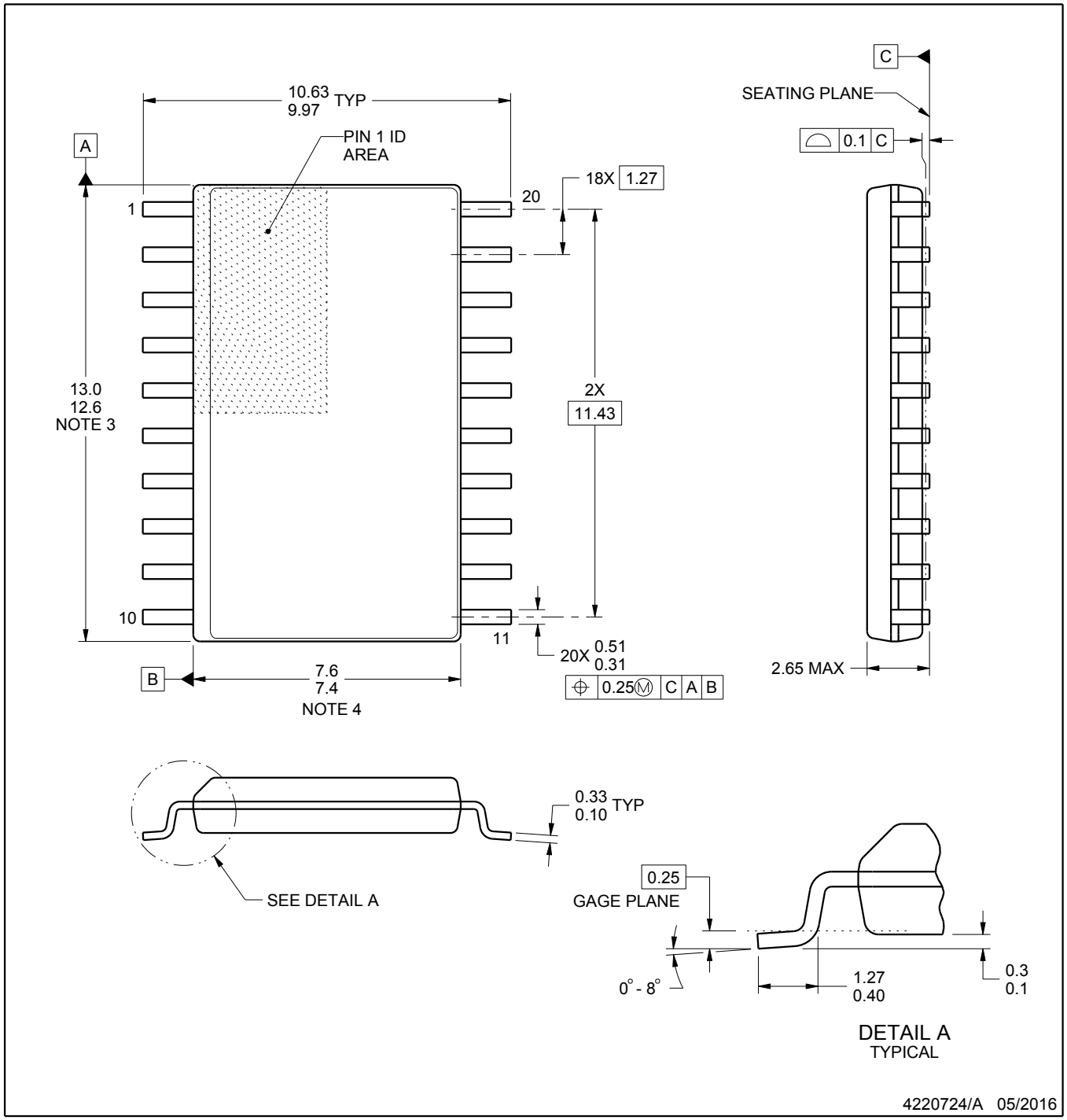


PACKAGE OUTLINE

DW0020A

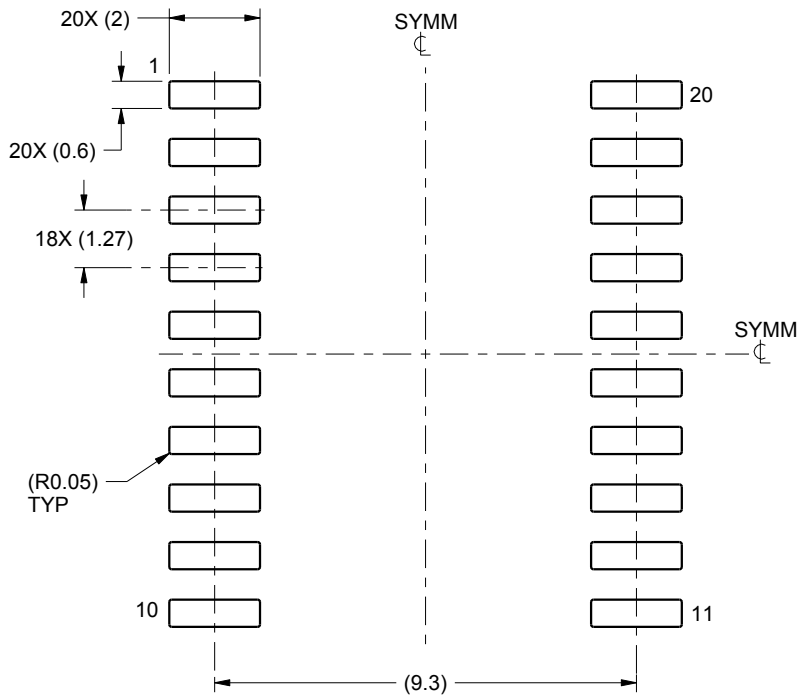
SOIC - 2.65 mm max height

SOIC

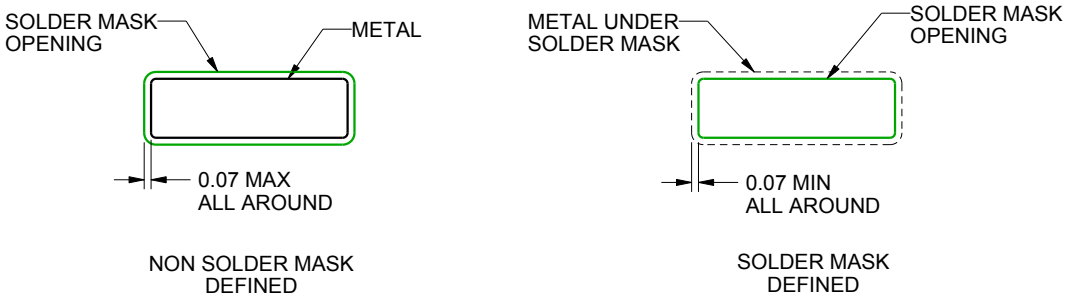


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X

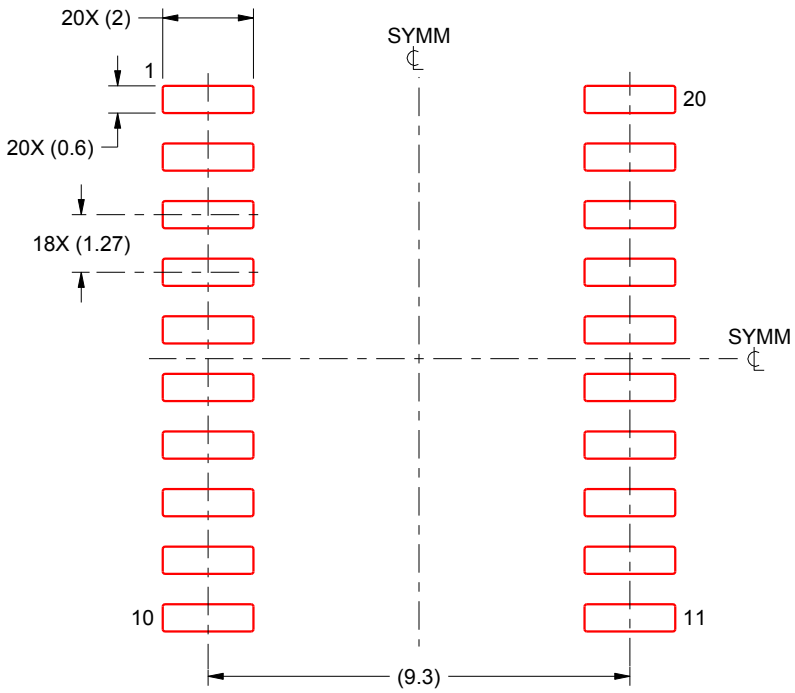


SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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>>TI(德州仪器)